

# CSD18509Q5B N-Channel NexFET™ Power MOSFETs

## 1 Features

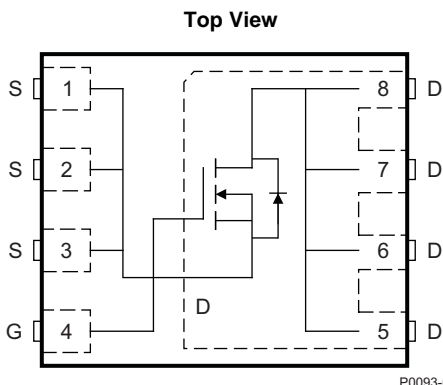
- Ultra-Low On Resistance
- Low Thermal Resistance
- Avalanche Rated
- Logic Level
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 5-mm x 6-mm Plastic Package

## 2 Applications

- DC-DC Conversion
- Secondary Side Synchronous Rectifier
- Motor Control

## 3 Description

This 40 V, 1 mΩ, SON 5 x 6 NexFET™ power MOSFET has been designed to minimize losses in power conversion applications.



### Product Summary

T <sub>A</sub> = 25°C		TYPICAL VALUE		UNIT
V <sub>DS</sub>	Drain-to-Source Voltage	40		V
Q <sub>g</sub>	Gate Charge Total (10 V)	150		nC
Q <sub>gd</sub>	Gate Charge Gate to Drain	17		nC
R <sub>DS(on)</sub>	Drain-to-Source On Resistance	V <sub>GS</sub> = 4.5 V	1.3	mΩ
		V <sub>GS</sub> = 10 V	1.0	mΩ
V <sub>GS(th)</sub>	Threshold Voltage	1.8		V

### Ordering Information<sup>(1)</sup>

Device	Qty	Media	Package	Ship
CSD18509Q5B	2500	13-Inch Reel	SON 5 x 6 mm Plastic Package	Tape and Reel
CSD18509Q5BT	250	7-Inch Reel		

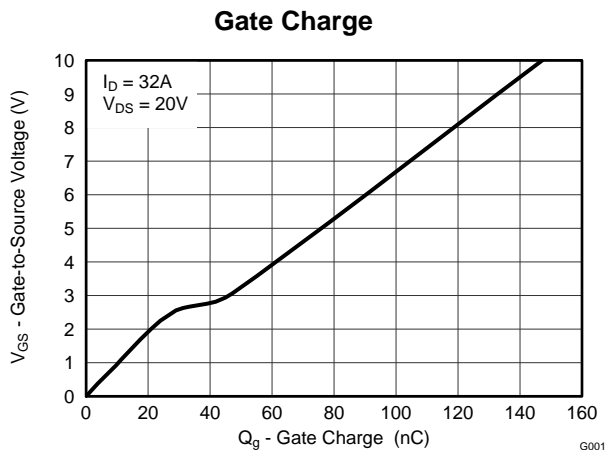
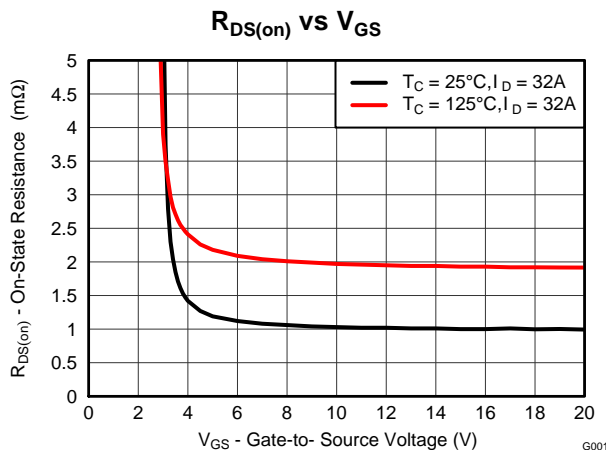
(1) For all available packages, see the orderable addendum at the end of the data sheet.

### Absolute Maximum Ratings

T <sub>A</sub> = 25°C		VALUE	UNIT
V <sub>DS</sub>	Drain-to-Source Voltage	40	V
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current (Package limited)	100	A
	Continuous Drain Current (Silicon limited), T <sub>C</sub> = 25°C	299	
	Continuous Drain Current <sup>(1)</sup>	38	
I <sub>DM</sub>	Pulsed Drain Current, T <sub>A</sub> = 25°C <sup>(2)</sup>	400	A
P <sub>D</sub>	Power Dissipation <sup>(1)</sup>	3.1	W
	Power Dissipation, T <sub>C</sub> = 25°C	195	
T <sub>J</sub> , T <sub>sig</sub>	Operating Junction and Storage Temperature Range	-55 to 150	°C
E <sub>AS</sub>	Avalanche Energy, single pulse I <sub>D</sub> = 83, L = 0.1 mH, R <sub>G</sub> = 25 Ω	345	mJ

(1) Typical R<sub>θJA</sub> = 40°C/W on a 1-inch<sup>2</sup>, 2-oz. Cu pad on a 0.06-inch thick FR4 PCB.

(2) Max R<sub>θJC</sub> = 0.8°C/W, Pulse duration ≤100 μs, duty cycle ≤1%



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## 4 Revision History

### Changes from Original (June 2014) to Revision A

**Page**

• Added the <i>Receiving Notification of Documentation Updates</i> and <i>Community Resources</i> sections to <i>Device and Documentation Support</i> . .....	<b>7</b>
• Changed the dimension between pads 3 and 4 from 0.028 inches: to 0.050 inches in the <i>Recommended PCB Pattern</i> section diagram .....	<b>9</b>

## 5 Specifications

### 5.1 Electrical Characteristics

 $(T_A = 25^\circ\text{C}$  unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>STATIC CHARACTERISTICS</b>						
$V_{DSS}$	Drain-to-Source Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	40			V
$I_{DSS}$	Drain-to-Source Leakage Current	$V_{GS} = 0\text{ V}, V_{DS} = 32\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate-to-Source Leakage Current	$V_{DS} = 0\text{ V}, V_{GS} = 20\text{ V}$			100	nA
$V_{GS(th)}$	Gate-to-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1.4	1.8	2.2	V
$R_{DS(on)}$	Drain-to-Source On Resistance	$V_{GS} = 4.5\text{ V}, I_D = 32\text{ A}$		1.3	1.7	m $\Omega$
		$V_{GS} = 10\text{ V}, I_D = 32\text{ A}$		1	1.2	m $\Omega$
$g_{fs}$	Transconductance	$V_{DS} = 4\text{ V}, I_D = 32\text{ A}$		180		S
<b>DYNAMIC CHARACTERISTICS</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 20\text{ V}, f = 1\text{ MHz}$	10700	13900		pF
$C_{oss}$	Output Capacitance		821	1070		pF
$C_{rss}$	Reverse Transfer Capacitance		272	354		pF
$R_G$	Series Gate Resistance		0.8	1.6		$\Omega$
$Q_g$	Gate Charge Total (4.5 V)	$V_{DS} = 20\text{ V}, I_D = 32\text{ A}$	70	91		nC
$Q_g$	Gate Charge Total (10 V)		150	195		nC
$Q_{gd}$	Gate Charge Gate-to-Drain		17			nC
$Q_{gs}$	Gate Charge Gate-to-Source		29			nC
$Q_{g(th)}$	Gate Charge at $V_{th}$		18			nC
$Q_{oss}$	Output Charge		$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$	39		
$t_{d(on)}$	Turn On Delay Time	$V_{DS} = 20\text{ V}, V_{GS} = 10\text{ V}, I_{DS} = 32\text{ A}, R_G = 0\ \Omega$	9			ns
$t_r$	Rise Time		19			ns
$t_{d(off)}$	Turn Off Delay Time		57			ns
$t_f$	Fall Time		11			ns
<b>DIODE CHARACTERISTICS</b>						
$V_{SD}$	Diode Forward Voltage	$I_{SD} = 32\text{ A}, V_{GS} = 0\text{ V}$	0.8		1	V
$Q_{rr}$	Reverse Recovery Charge	$V_{DS} = 20\text{ V}, I_F = 32\text{ A}, di/dt = 300\text{ A}/\mu\text{s}$	40			nC
$t_{rr}$	Reverse Recovery Time		23			ns

### 5.2 Thermal Information

 $(T_A = 25^\circ\text{C}$  unless otherwise stated)

THERMAL METRIC		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-Case Thermal Resistance <sup>(1)</sup>			0.8	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>(1)(2)</sup>			50	

- (1)  $R_{\theta JC}$  is determined with the device mounted on a 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inches × 1.5-inches (3.81-cm × 3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB.  $R_{\theta JC}$  is specified by design, whereas  $R_{\theta JA}$  is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu.



Max  $R_{\theta JA} = 50^{\circ}\text{C/W}$   
when mounted on  
1 inch<sup>2</sup> (6.45 cm<sup>2</sup>) of  
2-oz. (0.071-mm thick)  
Cu.



Max  $R_{\theta JA} = 125^{\circ}\text{C/W}$   
when mounted on a  
minimum pad area of  
2-oz. (0.071-mm thick)  
Cu.

### 5.3 Typical MOSFET Characteristics

( $T_A = 25^{\circ}\text{C}$  unless otherwise stated)

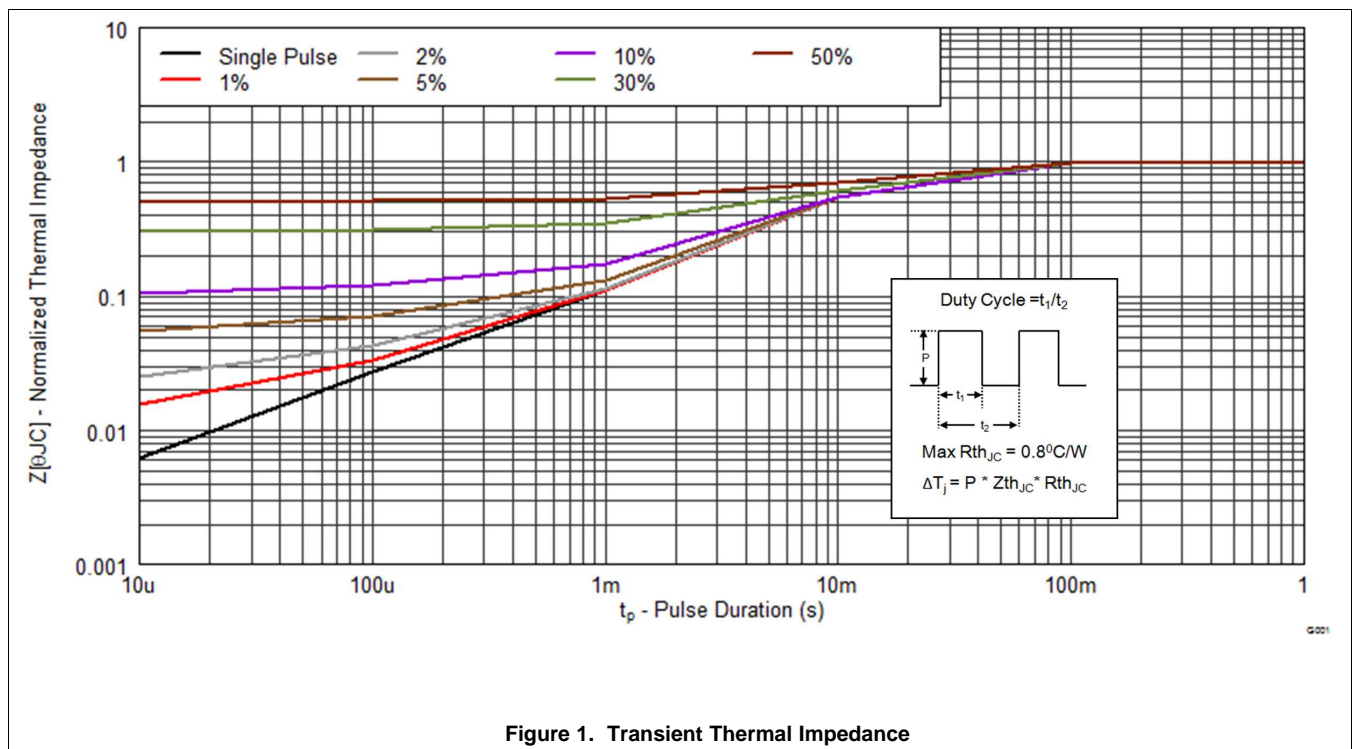


Figure 1. Transient Thermal Impedance

Typical MOSFET Characteristics (continued)

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

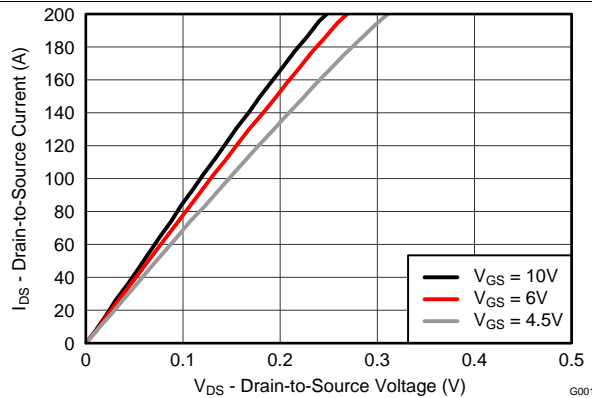


Figure 2. Saturation Characteristics

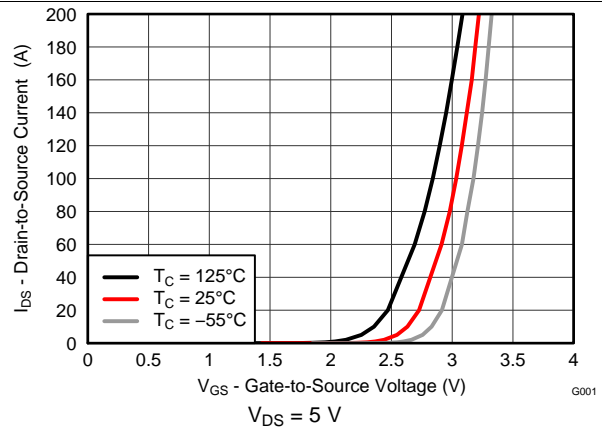


Figure 3. Transfer Characteristics

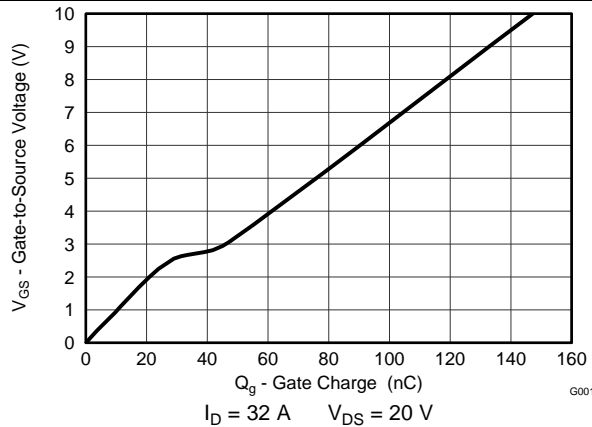


Figure 4. Gate Charge

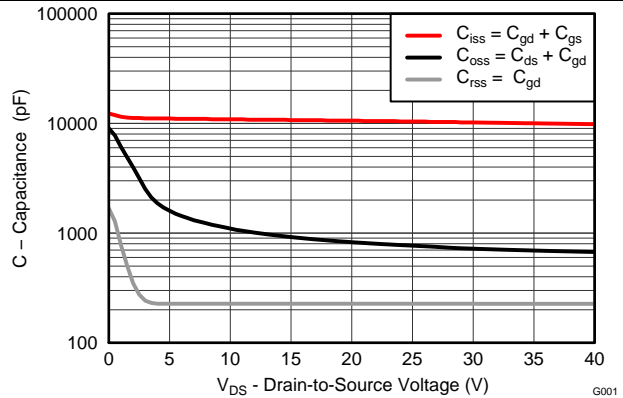


Figure 5. Capacitance

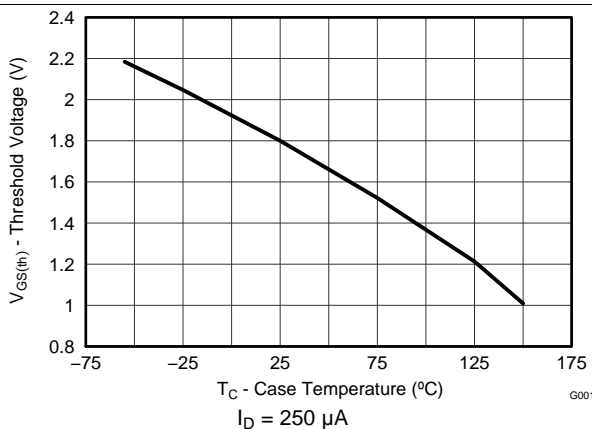


Figure 6. Threshold Voltage vs Temperature

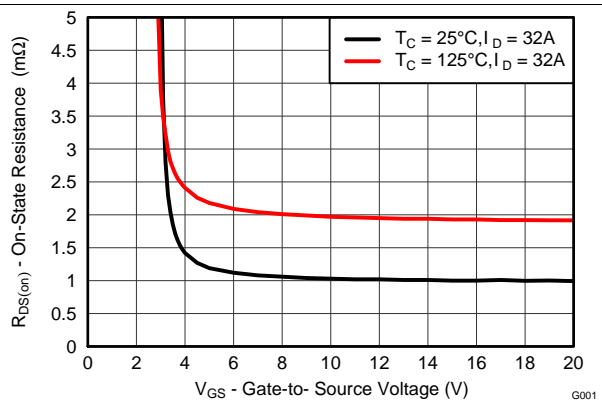


Figure 7. On-State Resistance vs Gate-to-Source Voltage

Typical MOSFET Characteristics (continued)

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

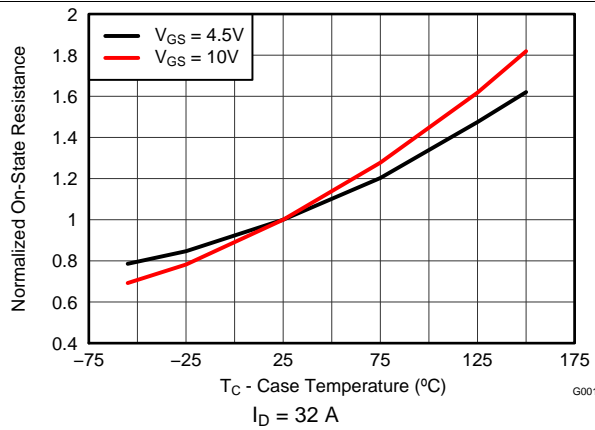


Figure 8. Normalized On-State Resistance vs Temperature

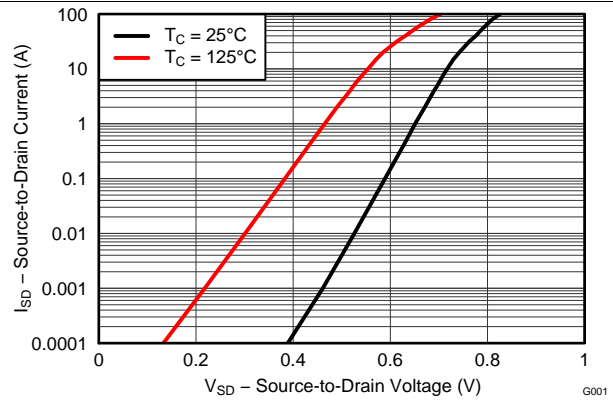


Figure 9. Typical Diode Forward Voltage

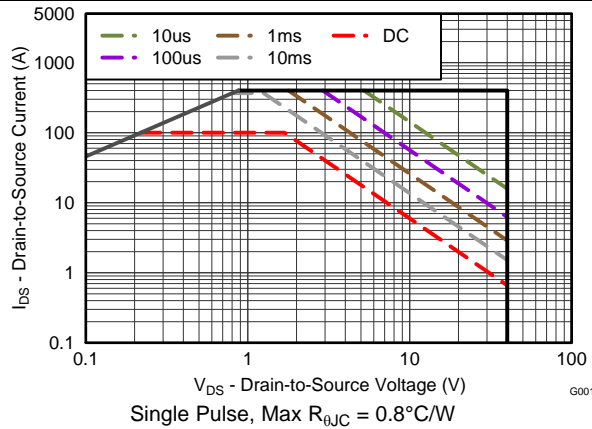


Figure 10. Maximum Safe Operating Area

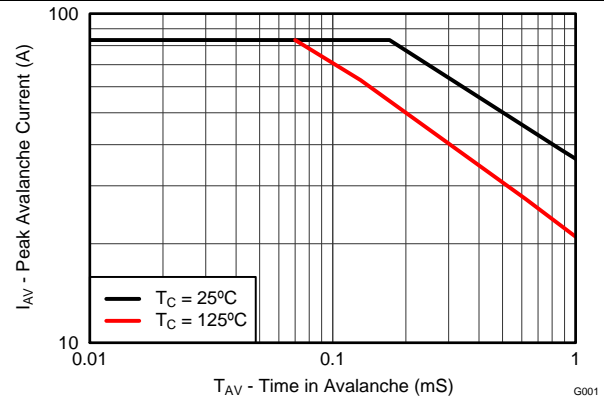


Figure 11. Single Pulse Unclamped Inductive Switching

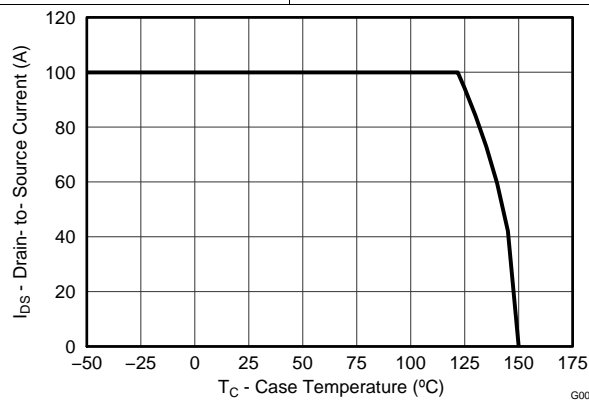


Figure 12. Maximum Drain Current vs Temperature

## 6 Device and Documentation Support

### 6.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 6.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 6.3 Trademarks

NexFET, E2E are trademarks of Texas Instruments.

### 6.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 6.5 Glossary

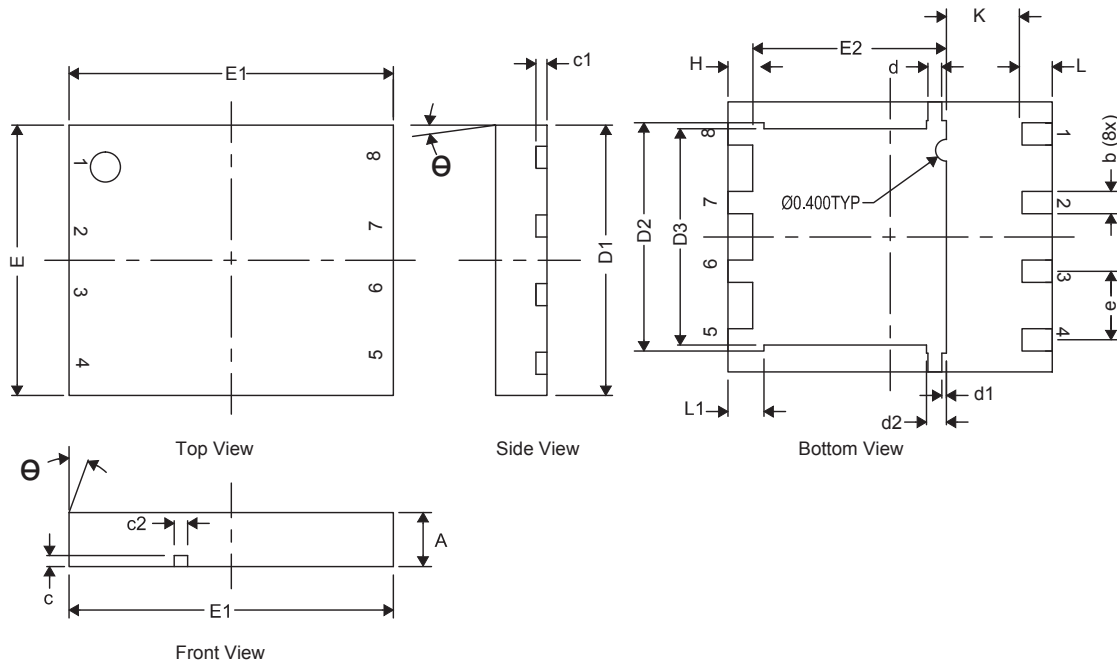
[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

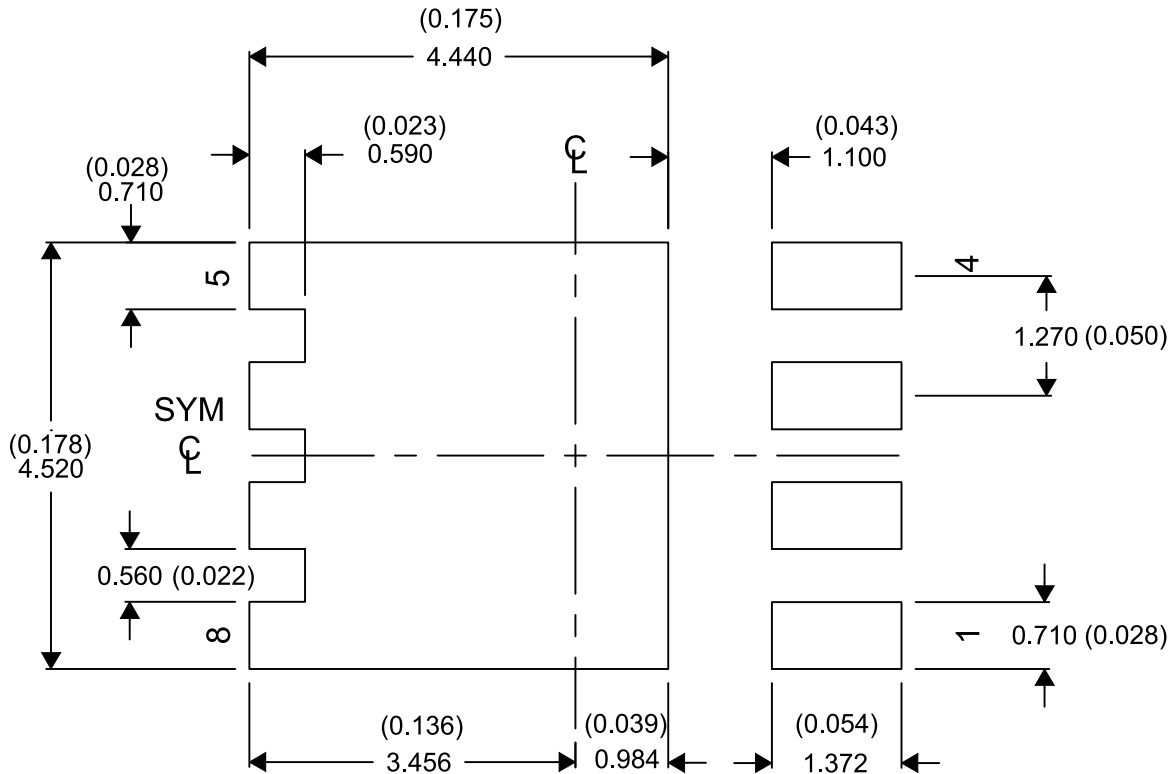
### 7.1 Q5B Package Dimensions



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.80	1.00	1.05
b	0.36	0.41	0.46
c	0.15	0.20	0.25
c1	0.15	0.20	0.25
c2	0.20	0.25	0.30
D1	4.90	5.00	5.10
D2	4.12	4.22	4.32
D3	3.90	4.00	4.10
d	0.20	0.25	0.30
d1	0.085 TYP		
d2	0.319	0.369	0.419
E	4.90	5.00	5.10
E1	5.90	6.00	6.10
E2	3.48	3.58	3.68
e	1.27 TYP		
H	0.36	0.46	0.56
L	0.46	0.56	0.66
L1	0.57	0.67	0.77
θ	0°	—	—
K	1.40 TYP		

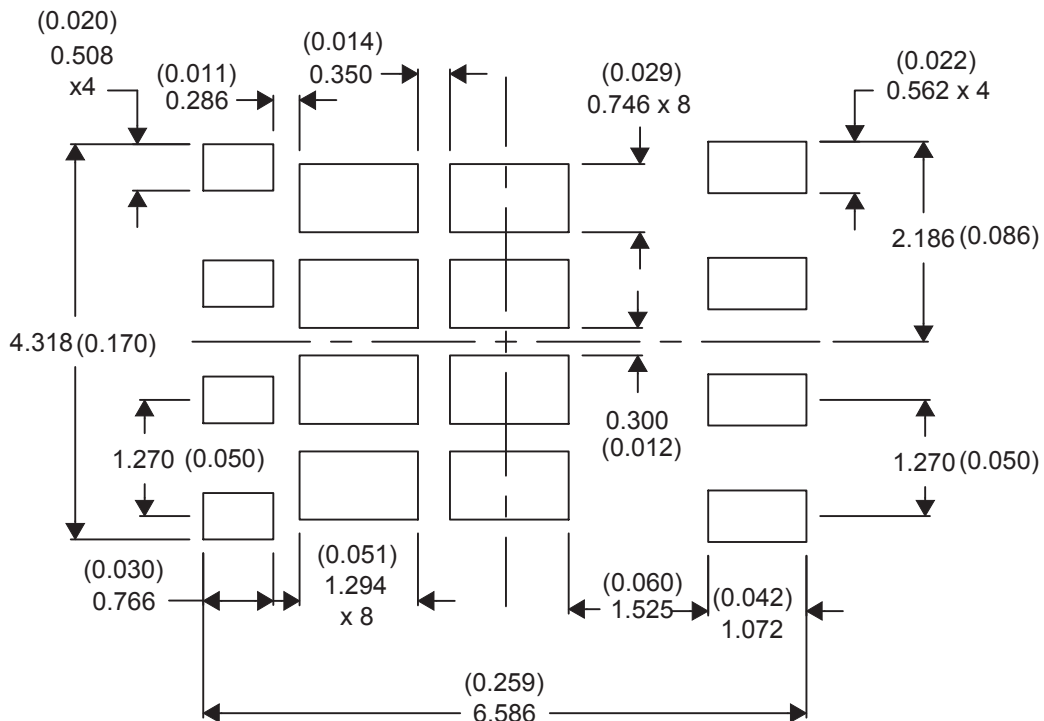


### 7.2 Recommended PCB Pattern



For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

### 7.3 Recommended Stencil Pattern

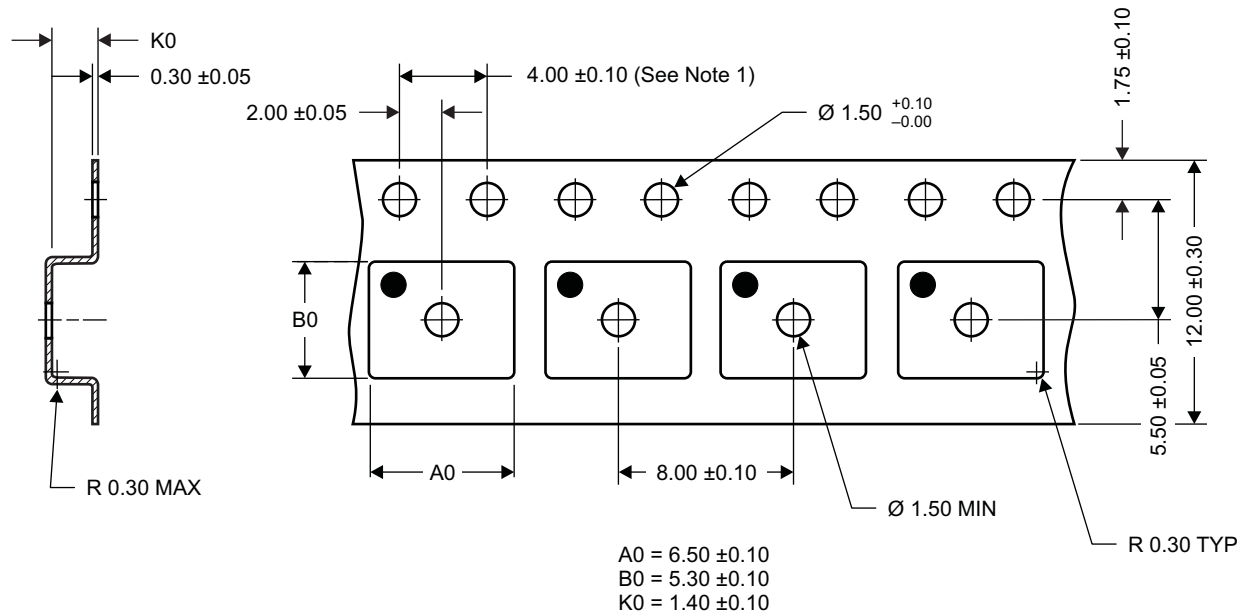


**CSD18509Q5B**

SLPS476A - JUNE 2014 - REVISED MAY 2017

[www.ti.com](http://www.ti.com)

**7.4 Q5B Tape and Reel Information**





M0138-01

**Notes:**

1. 10-sprocket hole-pitch cumulative tolerance  $\pm 0.2$
2. Camber not to exceed 1 mm in 100 mm, noncumulative over 250 mm
3. Material: black static-dissipative polystyrene
4. All dimensions are in mm (unless otherwise specified).
5. A0 and B0 measured on a plane 0.3 mm above the bottom of the pocket

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD18509Q5B	ACTIVE	VSON-CLIP	DNK	8	2500	RoHS-Exempt & Green	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 150	CSD18509	
CSD18509Q5BT	ACTIVE	VSON-CLIP	DNK	8	250	RoHS-Exempt & Green	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 150	CSD18509	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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